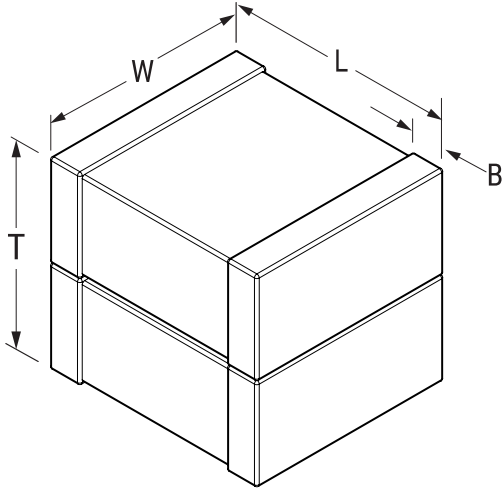




Click [here](#) for the 3D model.

General Information

Series	KONNEKT Comm X7R
Style	KONNEKT
Description	SMD, MLCC, KONNEKT, Ultra-Stable, Class II
Features	High Density Packaging
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	800 mg
Chip Size	2220-2
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.03 uF
Measurement Condition	120 Hz 0.5Vrms
Tolerance	10%
Voltage DC	3000 VDC
Dielectric Withstanding Voltage	3,600 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour
Insulation Resistance	33.3333 GOhms

Dimensions

L	5.7mm +/-0.4mm
W	5mm +/-0.4mm
T	5.1mm +/-0.4mm
B	0.6mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	300

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